

20V N-Channel Enhancement Mode MOSFET

VDS= 20V

RDS(ON), Vgs@ 2.5V, Ids@ 1.7A= 70mΩ

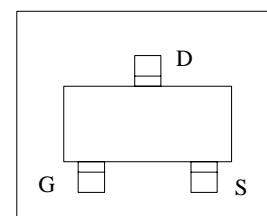
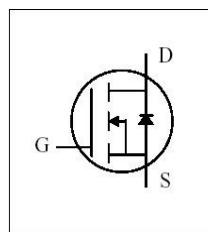
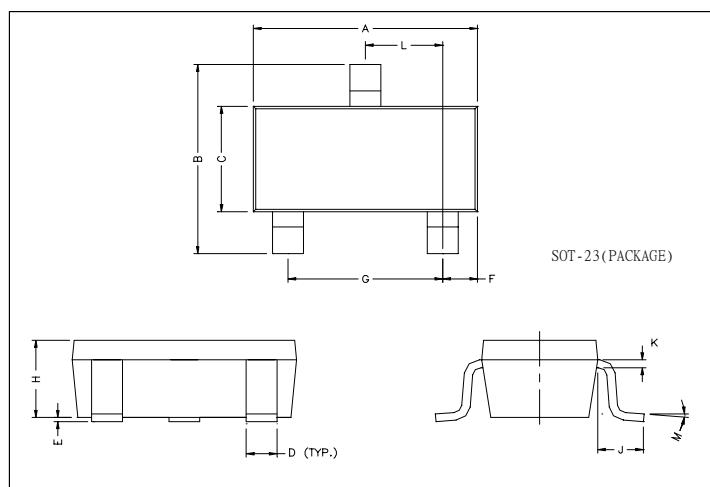
RDS(ON), Vgs@ 2.5V, Ids@ 1.5A= 100mΩ

Features

Advanced trench process technology

High Density Cell Design For Ultra Low On-Resistance

Package Dimensions



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	2.70	3.10	G	1.90	REF.
B	2.40	2.80	H	1.00	1.30
C	1.40	1.60	K	0.10	0.20
D	0.35	0.50	J	0.40	-
E	0	0.10	L	0.85	1.15
F	0.45	0.55	M	0°	10°

Maximum Ratings and Thermal Characteristics (TA = 25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	20	V
Gate-Source Voltage	V _{GS}	±8	
Continuous Drain Current	I _D	1.7	A
Pulsed Drain Current ¹⁾	I _{DM}	8	
Maximum Power Dissipation ²⁾	P _D	1.25	W
		0.8	
Operating Junction and Storage Temperature Range	T _J , T _{stg}	-55 to 150	°C
Junction-to-Ambient Thermal Resistance (PCB mounted) ²⁾	R _{thJA}	100	°C/W
Junction-to-Ambient Thermal Resistance (PCB mounted) ³⁾		166	

Notes

1) Pulse width limited by maximum junction temperature.

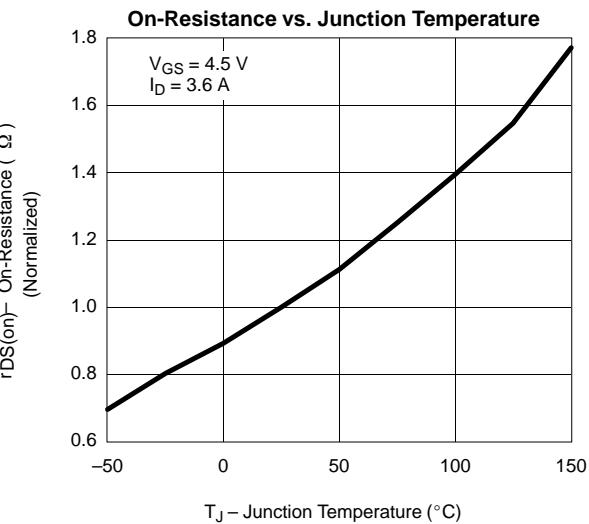
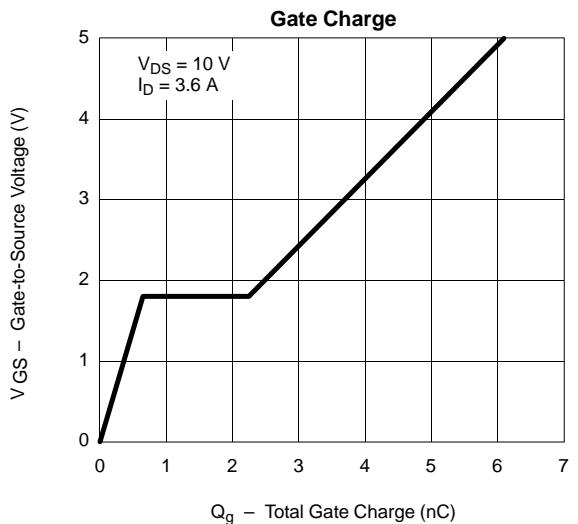
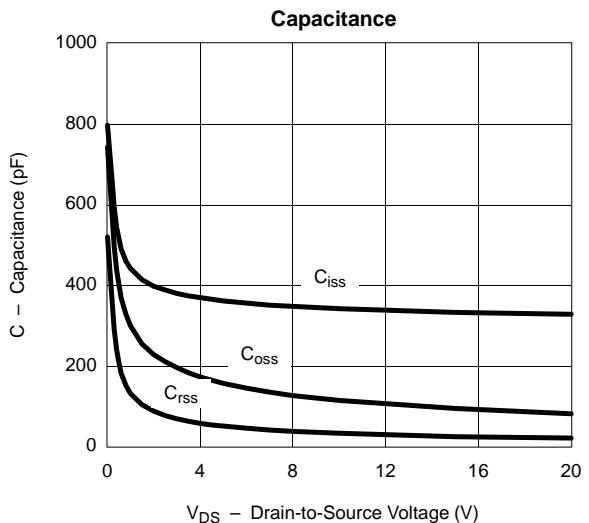
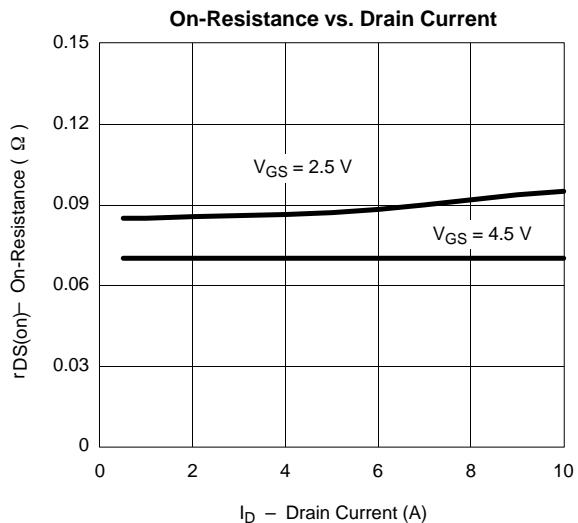
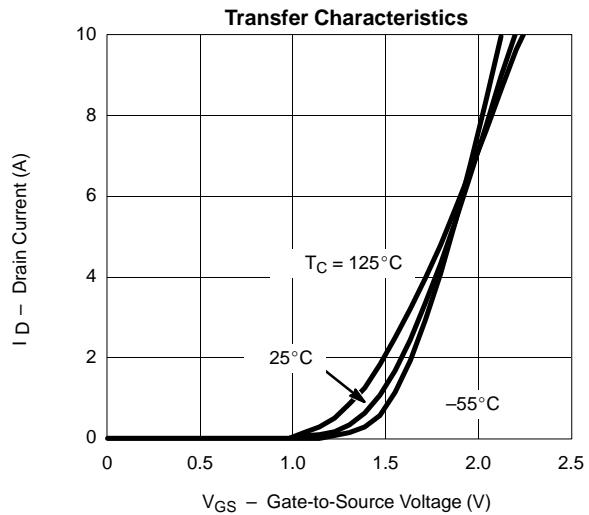
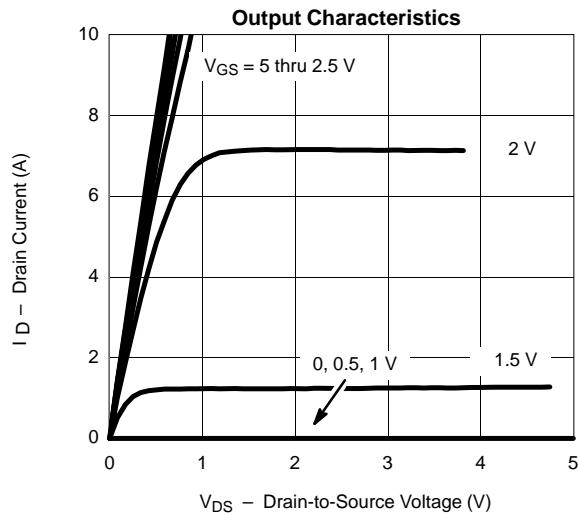
2) Surface Mounted on FR4 Board, t ≤ 5 sec.

3) Surface Mounted on FR4 Board.

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ELECTRICAL CHARACTERISTICS

Parameter	Symbol	Test Condition	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS} = 0V, I_D = 10\mu A$	20			V
Drain-Source On-State Resistance ¹⁾	$R_{DS(on)}$	$V_{GS} = 4.5V, I_D = 1.7A$		55	70	$m\Omega$
		$V_{GS} = 2.5V, I_D = 1.5A$		78	100	
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 50\mu A$	0.4		1.5	V
Zero Gate Voltage Drain Current 0	I_{DSS}	$V_{DS} = 16V, V_{GS} = 0V$		1		μA
Gate Body Leakage	I_{GSS}	$V_{GS} = \pm 8V, V_{DS} = 0V$			± 100	nA
Forward Transconductance ¹⁾	g_{fs}	$V_{DS} = 5V, I_D = 1.5A$		7		S
Dynamic¹⁾						
Total Gate Charge	Q_g	$V_{DS} = 10V, I_D = 3.6A$ $V_{GS} = 4.5V$		5.4	10	nC
Gate-Source Charge	Q_{gs}			0.65		
Gate-Drain Charge	Q_{gd}			1.6		
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 10V, RL = 5.5\Omega$ $I_D \approx 3.6A, V_{GEN} = 4.5V$ $R_G = 6\Omega$		12	25	ns
Turn-On Rise Time	t_r			36	60	
Turn-Off Delay Time	$t_{d(off)}$			34	60	
Turn-Off Fall Time	t_f			10	25	
Input Capacitance	C_{iss}	$V_{DS} = 10V, V_{GS} = 0V$ $f = 1.0 \text{ MHz}$		340		pF
Output Capacitance	C_{oss}			115		
Reverse Transfer Capacitance	C_{rss}			33		
Source-Drain Diode						
Max. Diode Forward Current	I_S				0.6	A
Diode Forward Voltage	V_{SD}	$I_S = 1.6A, V_{GS} = 0V$			1.2	V

¹⁾ Pulse test: pulse width <= 300us, duty cycle<= 2%

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